



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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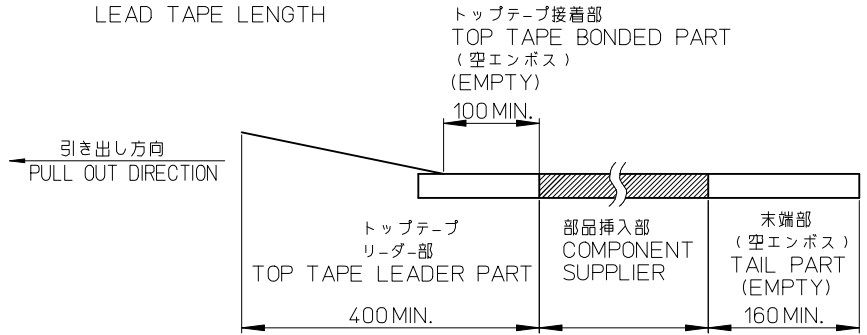
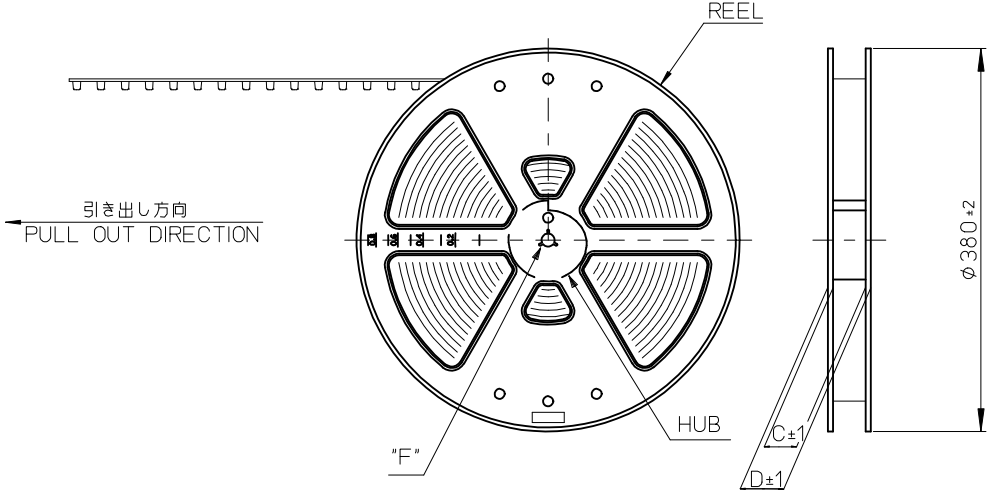
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



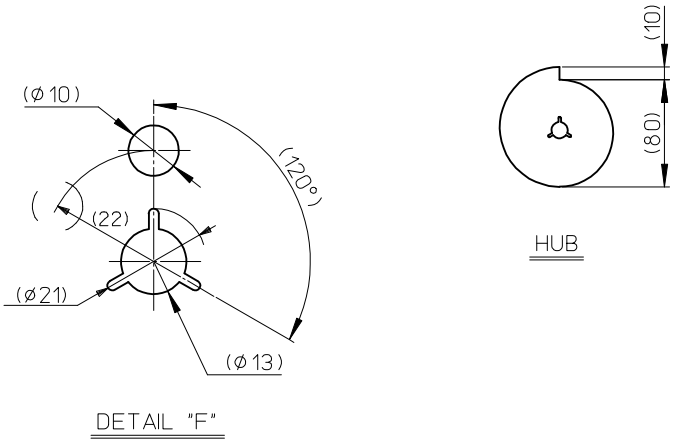
ELV AND RoHS COMPLIANT.

NOTES

1. 梱包数量：900 個/リール
NUMBER OF CONNECTORS:900 PCS/REEL
2. リードテープ長さ
LEAD TAPE LENGTH



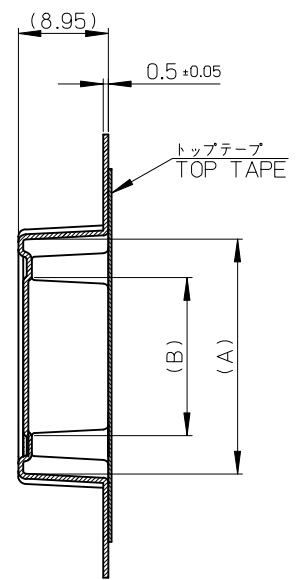
3. 製品詳細寸法については図面 SD-501786-008を参照下さい。
RE DETAILED DIMENSION, SEE SD-501786-008.
4. 材料(MATERIAL)
キャリアテープ(CARRIER TAPE)：ポリスチレン(POLYSTYRENE)
トップテープ(TOP TAPE)：PET, PE, PE
リール(REEL)：ポリスチレン(POLYSTYRENE)<リサイクル材を含む>
<RECYCLE MATERIAL CONTAINED>
5. ELV及びRoHS適合品
ELV AND RoHS COMPLIANT



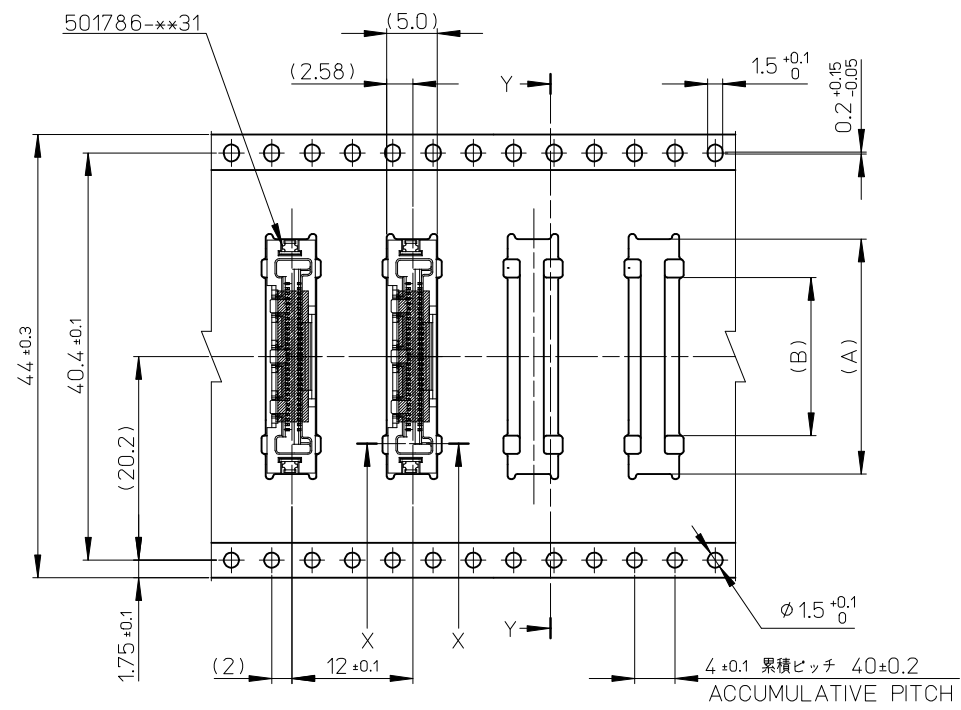
501786-**91 MODEL NO.

| | | | | | | | |
|--|---------------------------------------|--|-----------------------------|------------------|--|------------------------|------------------------|
| REVISED EC NO: J2009-1986 DRWN:YSHIBATA 2009/02/26 CHKD:THARUYAMA 2009/02/26 APPR:NUKITA 2009/02/26 REV A | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION |
| | 10 UNDER | ±0.2 | DRAWN BY H. IJIMA | DATE 07/12/25 | TITLE EMBSTP PKG FOR 0.5 FFC TO BOARD ST TYPE | | |
| | 10 OVER 30 UNDER | ±0.25 | CHECKED BY K. MORIKAWA | DATE 07/12/25 | MOLEX INCORPORATED | | |
| | 30 OVER | ±0.3 | APPROVED BY H. HIRATA | DATE 07/12/25 | DOCUMENT NO. SD-501786-009 | | |
| | ANGULAR ±3 ° | | MATERIAL NO. 501786-**91 | | SHEET NO. 1 OF 2 | | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | | |

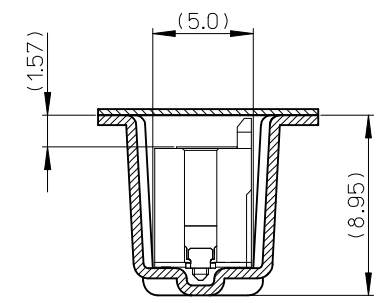
引き出し方向
PULL OUT DIRECTION



SECT. Y-Y



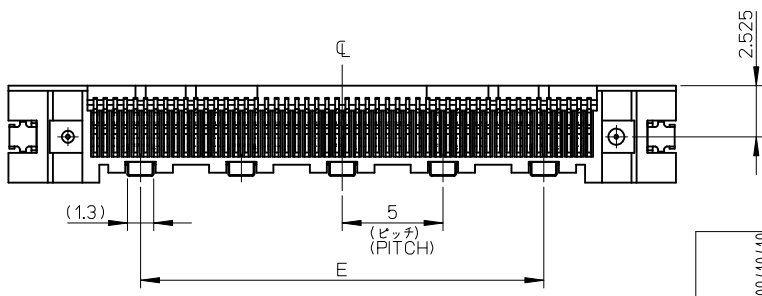
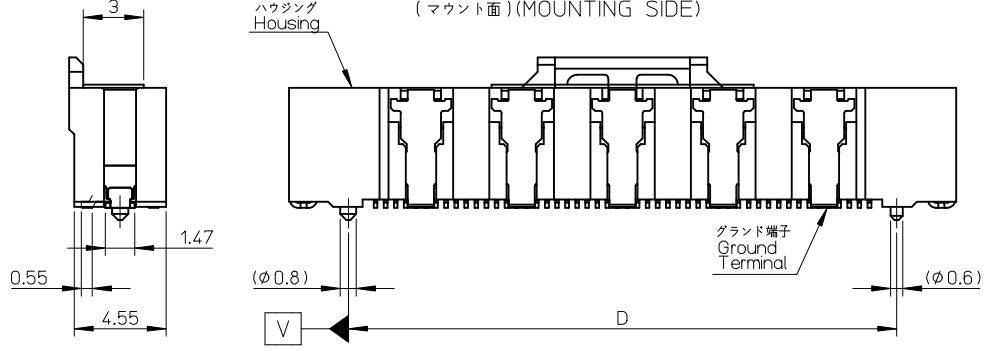
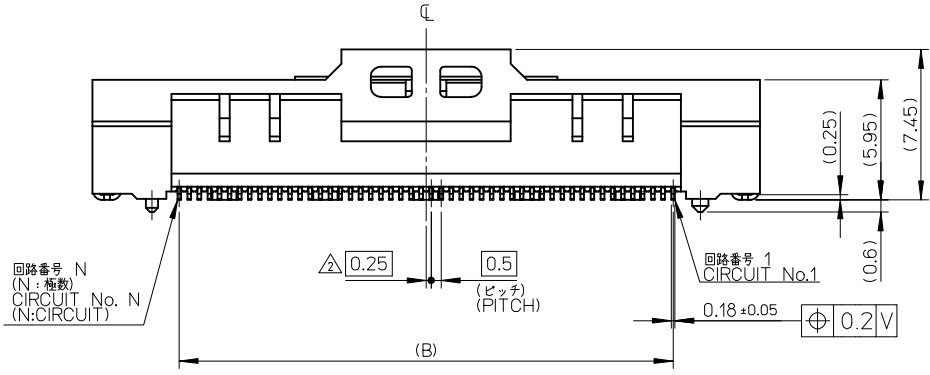
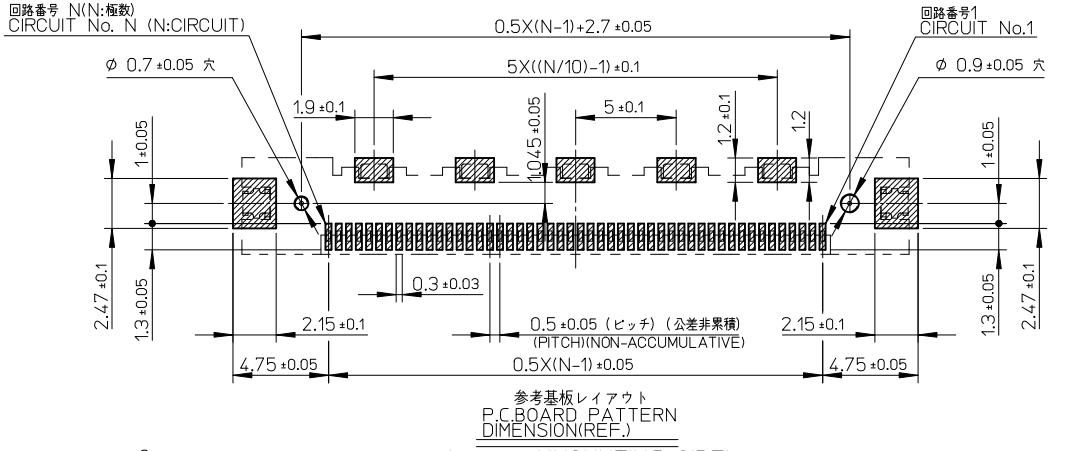
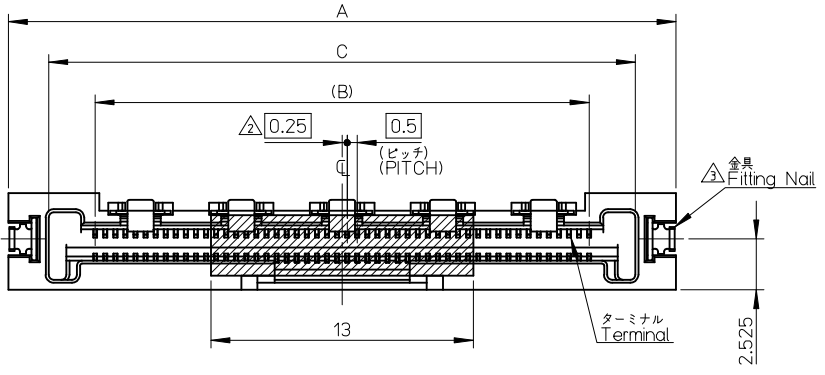
44mm幅キャリアテープ
44mm WIDTH CARRIER TAPE



SECT. X-X

| | | | | | | |
|--------------------------------|------|------|-------|------|----------------------|-----------|
| 56 | 61.4 | 57.4 | 25.68 | 33.3 | 501786-5091 | 50 |
| 44 | 49.4 | 45.4 | 15.68 | 23.3 | 501786-3091 | 30 |
| キャリアテープ幅 CARRIER TAPE WIDTH | D | C | B | A | 製品番号 MATERIAL NO. | 極数 CKT |

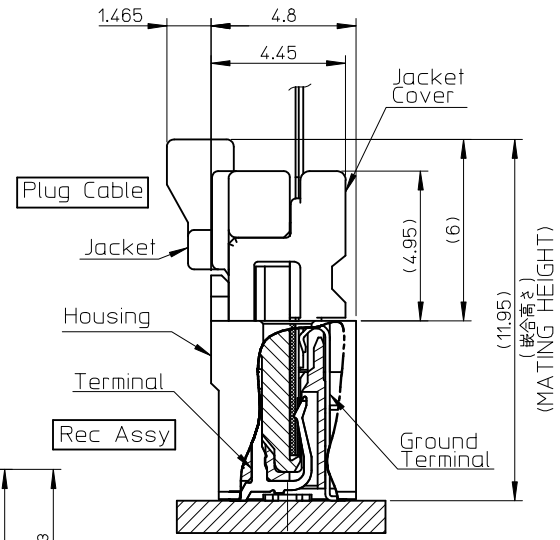
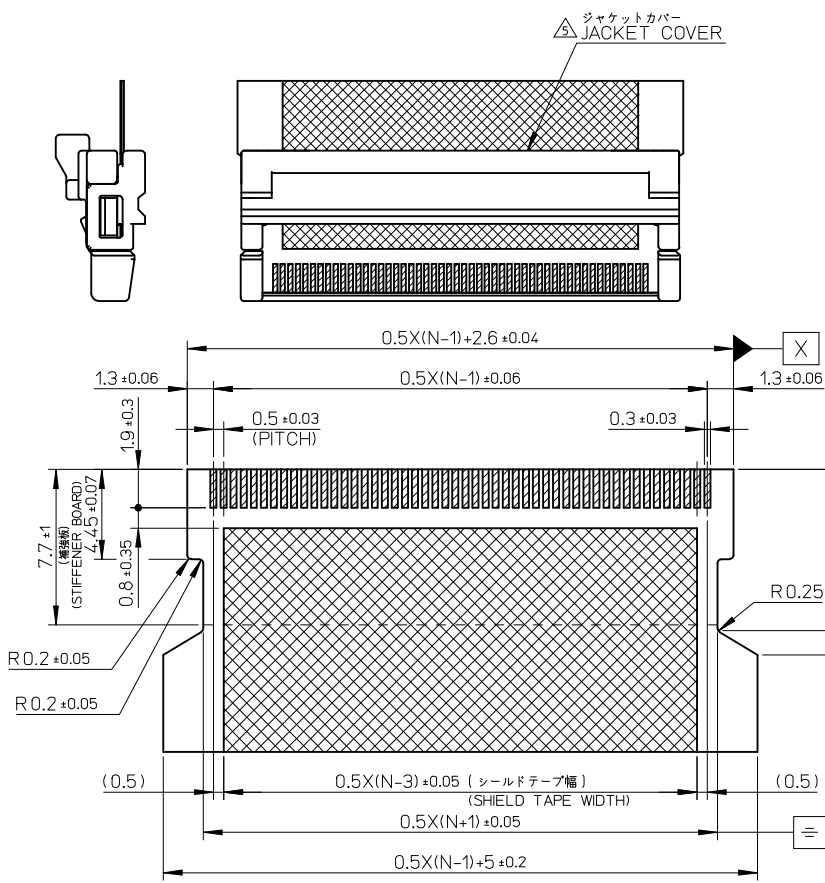
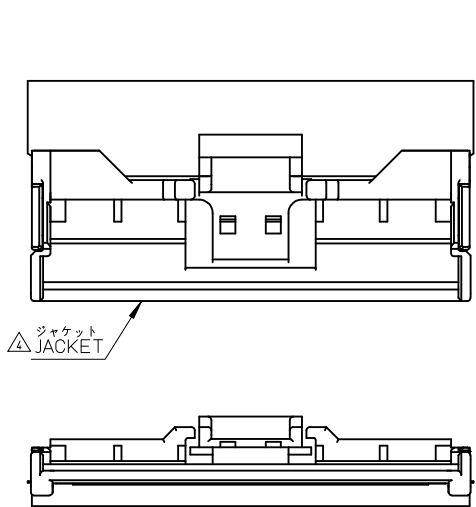
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|--|--|----------------------------|------------------|--|-------------------------------|---------------------|--|
| REVISED EC NO: J2009-1986 DRWN: YSHIBATA 2009/02/26 CHKD: THARUYAMA 2009/02/26 APPR: NUKITA 2009/02/26 | DESCRIPTION GENERAL TOLERANCES (UNLESS SPECIFIED) 10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 ANGULAR ±3° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | DIMENSION STYLE MM ONLY | SCALE --- | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | | |
| | | DRAWN BY H. IJIMA | DATE 07/12/25 | TITLE EMBSTP PKG FOR 0.5 FFC TO BOARD ST TYPE | | | |
| | | CHECKED BY K. MORIKAWA | DATE 07/12/25 | MOLEX INCORPORATED | | | |
| | | APPROVED BY H. HIRATA | DATE 07/12/25 | MATERIAL NO. 501786-**91 | DOCUMENT NO. SD-501786-009 | SHEET NO. 2 OF 2 | |



| | | | | | | | |
|--------------------|----|------|------|------|------|--------------------|------------|
| 5 | 20 | 27.2 | 29.1 | 24.5 | 33.1 | 501786-5091 | 50 |
| QTY of Ground Term | E | D | C | B | A | EMBOSSED TAPE PKG. | 極数 CIRCUIT |
| | | | | | | ORDER No. オーダー番号 | |

CONNECTOR SERIES No. 501786-**31

| | | | | | | | | | |
|---|---------------------------------------|--|----------------------------|--------------------|---|------------------------|--|------------------------|--|
| REVISED EC NO: J2010-0779 DRWN: NISHI 2009/10/19 CHKD: MATSUURA 2009/10/19 APPR: KMORIKAWA 2009/10/19 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE --- | DESIGN UNITS METRIC | | THIRD ANGLE PROJECTION | |
| | 10 UNDER | ±0.2 | DRAWN BY YSHIBATA | DATE 2009/02/17 | TITLE 0.5 FFC TO BOARD CONN REC HSG ASSY (ST) | | | | |
| | 10 OVER 30 UNDER | ±0.25 | CHECKED BY THARUYAMA | DATE 2009/02/17 | MOLEX INCORPORATED | | | | |
| | 30 OVER | ±0.3 | APPROVED BY NUKITA | DATE 2009/02/17 | DOCUMENT NO. SD-501786-012 | | | | |
| | ANGULAR ±1 ° | | MATERIAL NO. SEE CHART | | SHEET NO. 1 OF 2 | | | | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | | | | |



嵌合断面図
MATED CONNECTOR SECTION

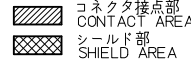
注記
NOTE

1. 使用材料 MATERIAL

- ハウジング HOUSING : 液晶ポリマー (LCP), ガラス充填, UL94V-0 色: 黒色
LIQUID CRYSTAL POLYMER(LCP), GLASS FILLED, UL94V-0 COLOR: BLACK
- ターミナル TERMINAL : 焼青銅 (τ=0.18)
PHOSPHOR BRONZE (τ=0.18)
- メッキ PLATING : コンタクト部: 部分金めっき (0.1μm以上)
テル部: 部分金めっき
下地: ニッケルめっき (1.0μm以上)
- CONTACT AREA : SEPARATED GOLD PLATING (0.1μm MINIMUM)
- SOLDER TAIL AREA : SEPARATED GOLD PLATING
- UNDER PLATING : NICKEL OVERALL (1.0μm MINIMUM)
- 金具 FITTING NAIL : 焼青銅 (τ=0.25)
ニッケル下地 錫メッキ (1.0μm以上)
PHOSPHOR BRONZE (τ=0.25)
TIN OVER NICKEL PLATING (1.0μm MINIMUM)
- グラウンド端子 GROUND TERMINAL : 焼青銅 (τ=0.15)
ニッケル下地 錫メッキ (1.0μm以上)
PHOSPHOR BRONZE (τ=0.15)
TIN OVER NICKEL PLATING (1.0μm MINIMUM)

適合する金めっきFFC推奨寸法
APPLICABLE FFC OF GOLD PLATING
RECOMENDED DIMENSION

(仕上がり厚さ: コネクタ接点部 0.3±0.03)
シールド部 0.44±0.05)
(THICKNESS : CONTACT AREA 0.3±0.03)
SHIELD AREA 0.44±0.05)



6.FFCについて
ABOUT FFC

打ち抜き方向は導体側から補強板側を推奨します。
導体部については軟箔銅35μmまたは50μmを推奨します。
RECOMMENDED PUNCHING DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER SIDE
RECOMMENDED CONDUCTOR SPEC : SOFT COPPER FOIL
RECOMMENDED CONDUCTOR THICKNESS : 35MICROMETER OR 50MICROMETER

7.ELV及びRoHS適合品

ELV AND RoHS COMPLIANT

- △2 N=偶数に適用 (N:極数)
APPLY FOR N-EVEN IN CIRCUIT)
- △3 パターン剥離止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B PATTERN.
- △4 適合ジャケット: 503150-**-09
製品詳細寸法はSD-503150-001を参照下さい。
APPLICABLE JACKET: 503150-**-09
RE DETAILED DIMENSION, SEE 'SD-503150-001.
- △5 適合ジャケットカバー: 503151-**-09
製品詳細寸法はSD-503151-001を参照下さい。
APPLICABLE JACKET: 503151-**-09
RE DETAILED DIMENSION, SEE 'SD-503151-001.

| | | | | | | | | | |
|---|-------------|---|-------|----------------------------|------------|--------------------|--|------------------------|--|
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| | | 10 UNDER | ±0.2 | DRAWN BY | DATE | TITLE | 0.5 FFC TO BOARD CONN REC HSG ASSY (ST) | | |
| | | 10 OVER 30 UNDER | ±0.25 | CHECKED BY | DATE | MOLEX INCORPORATED | | | |
| | | 30 OVER | ±0.3 | APPROVED BY | DATE | | | | |
| | | ANGULAR | ±1 ° | NUKITA | 2009/02/17 | SEE SHEET 1 | SD-501786-012 | 2 OF 2 | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | | | | |